



Material Content Data Sheet



Sales Product Name		IPS110N12N3 G		Issued		20. July 2018		
MA#		MA001300680						
Package		PG-TO251-3-11		Weight*		383.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.755	1.50	1.50	15023	15023
leadframe	non noble metal	iron	7439-89-6	0.225	0.06		587	
	inorganic material	phosphorus	7723-14-0	0.068	0.02		176	
	non noble metal	copper	7440-50-8	224.739	58.68	58.76	586646	587409
wire	non noble metal	aluminium	7429-90-5	3.866	1.01	1.01	10090	10090
encapsulation	organic material	carbon black	1333-86-4	1.194	0.31		3118	
	inorganic material	antimonytrioxide	1309-64-4	2.389	0.62		6236	
	plastics	brominated resin	-	2.389	0.62		6236	
	plastics	epoxy resin	-	23.889	6.24		62359	
	inorganic material	silicondioxide	60676-86-0	89.585	23.38	31.17	233848	311797
leadfinish	non noble metal	tin	7440-31-5	3.597	0.94	0.94	9389	9389
plating	non noble metal	nickel	7440-02-0	0.090	0.02		235	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	236
solder	noble metal	silver	7440-22-4	0.117	0.03		304	
	non noble metal	tin	7440-31-5	0.093	0.02		243	
	non noble metal	lead	7439-92-1	4.452	1.16	1.21	11622	12169
heatspreader	non noble metal	iron	7439-89-6	0.021	0.01		54	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	20.617	5.38	5.39	53817	53887
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com